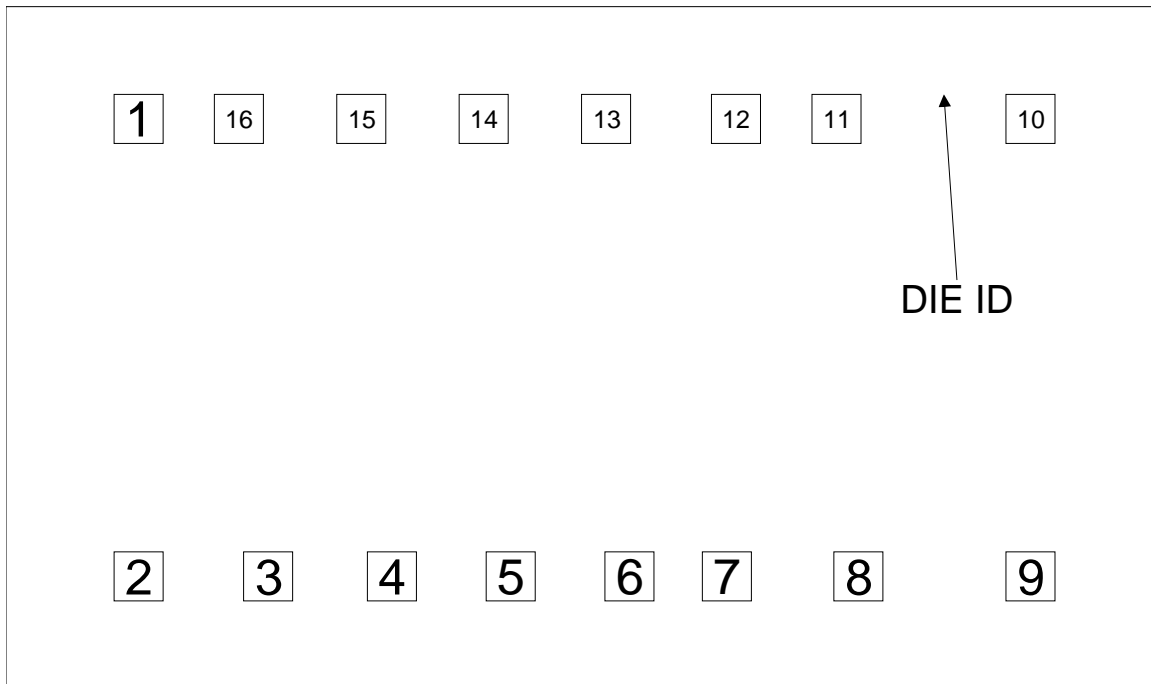


ADC128S102 MDR MCD3070A
8-Channel, 50 kSPS to 1 MSPS, 12-Bit A/D Converter

AUG 19, 2009

DIE LAYOUT (A-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	ADC128HR	Bond Pad Opening Size (min)	77.00µm x 77.00µm
Die Step	A	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	PECVDOX NITRIDE
Wafer Diameter	200mm	Back Side Metal	Bare Back
Die Size (Drawn)	1808.48µm x 1071.88µm 71.2mils x 42.2mils	Back Side Connection	Floating or GND
Thickness	304.8µm Nominal		
Min Pitch	153.00µm		

Note: All values are rounded to the nearest micron.

Special Assembly Requirements:

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Die Bond Pad Coordinate Locations(A-Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X	Y	
	1	-696	359	77	x	77
	2	-696	-359	77	x	77
	3	-493	-359	77	x	77
	4	-299	-359	77	x	77
	5	-112	-359	77	x	77
	6	75	-359	77	x	77
	7	228	-359	77	x	77
	8	434	-359	77	x	77
	9	704	-359	77	x	77
	10	704	359	77	x	77
	11	400	359	77	x	77
	12	242	359	77	x	77
	13	38	359	77	x	77
	14	-154	359	77	x	77
	15	-347	359	77	x	77
	16	-539	359	77	x	77

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Notes

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